

Amendments to Claims

1. (Cancelled)

2. (Cancelled)

3. (Cancelled)

4. (Cancelled)

5. (Cancelled)

6. (Cancelled)

7. (Cancelled)

8. (Cancelled)

9. (Cancelled)

10. (Cancelled)

11. (Cancelled)

12. (Cancelled)

13. (Cancelled)

14. (Cancelled)

15. (Currently Amended) A process for forming of an organic electronic device comprising:

forming a patterned electrically conductive layer over a substrate, wherein the patterned electrically conductive layer comprises an electrically conductive member for the organic electronic device; and

selectively forming spaced-apart members, wherein:

a heat sink comprises the spaced-apart members;

the spaced-apart members are spaced apart from each other; and

the spaced-apart members are thermally coupled to the electrically conductive member.

16. (Original) The process of claim 15, further comprising placing a first stencil mask over the patterned electrically conductive layer before selectively forming the spaced-apart members, wherein the first stencil mask has openings corresponding to shapes of the spaced-apart members.

17. (Original) The process of claim 16, further comprising placing a second stencil mask over the substrate before forming the patterned electrically conductive layer, wherein:

the second stencil mask has an opening corresponding to a shape of the electrically conductive member; and

selectively forming is performed by a method selected from the group consisting of vapor depositing, coating, casting, and printing.

18. (Original) The process of claim 15, wherein selectively forming comprises plating an electrically conductive material.

19. (Currently Amended) The process of claim 18, further comprising forming a patterned insulating layer before selectively forming, wherein the patterned insulating layer has openings corresponding to locations where the second members will be formed during selectively forming.

20. (Original) A process for forming an organic electronic device comprising:
forming a first layer over a substrate;
forming a patterned resist layer over the first layer, wherein an exposed portion of the first layer underlies an opening within the patterned resist layer; and
etching at least partially through the exposed portion of the first layer,
wherein a heat sink comprises first layer.

21. (Original) The process of claim 20, wherein etching comprises wet etching.

22. (Original) The process of claim 20, wherein etching comprises dry etching.

23. (Cancelled)

24. (Cancelled)

25. (Cancelled)

26. (Cancelled)

27. (New) The process of claim 15, wherein the electrically conductive member is an electrode for the organic electronic device.